

## INFORMATION NOTE

**Date** 18.04.2016  
**No.** 001-16

### TRACO POWER TES 1 Series

#### Product change for improved consistency under reflow soldering process

Subject product series has undergone a minor, non dimension related package design change. The package of this insert mould (unpotted, non-hermetically sealed) SMD component consists of glue-bonded top and bottom plastic capsules. The seamline bonding changes from currently three sides to bonding of all four sides. A new vent hole, added to the component surface, will ensure the unobstructed, exactly defined thermal pressure exchange. Purpose of this change is a manufacturing process consistency improvement of the component in relation with its reflow processing suitability. This supports sustainable solder joint quality, since the component may not unintentionally be displaced on the carrier board caused by reflow temperature surges.

#### Note:

TES 1 Series will maintain non fully hermetical seamlines hence, for potential risk of liquid ingress and residue, the product remains to be unsuitable for any kind of washing process.

#### Timeline:

The product change is active for all dual output models since production date 2015 CW36. For single output models the product change will be phased in commencing in May 2016.

#### Change details:

Phased out package design



New package design



Product drawings are available in the [TES 1 Datasheet](#) or via the [TES 1 Product Overview](#). For further support please visit [www.tracopower.com](http://www.tracopower.com) or contact your sales point or TRACO.

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